IPC ASSOCIATION CONNELECTRONICS INDU	Material Comp © Copyright 2005. international and Pa	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materia	ials and Mfg Information				
upplier Inf	formation						·									
Company name	e*	Company unique ID			Ţ	Unique ID Authority					Response Date*					
nsemi												2024-04-25				
Contact Name		Title - Contact			I	Phone - Contact*					Email - Contact*					
Product-Env-S	Stewards	Product Enviro Compliance]	NA					Product-Env-Stewards@onsemi.com					
uthorized Rep	presentative*	Title - Representative			I	Phone - Representative*				Email - Representative*						
Product-Env-S	Stewards	Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com					
Req	Requester Item Number Mfr Ite		em Number Mfr Item Name				Effective Date Version Manufacturing S.		ing Site		Weight*	UOM	Unit Type			
		NCP1093MNG HINT OAC		HINT OAC DFN1	AC DFN10 NCP1093MNG		2024-04-25			PHG		2	25.48	mg	Each	
Ianufactur	ring Process Informa	ation														
Term	Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temper		dy Temperat	nture Max Time at Peak Temp		Temperat	ure Num	ber of Reflow Cyo	eles	
Matte Tin (Sn) - annealed			CU Alloy 3			260 C 30		30		secon	ds 3					
omments																
TTENTION:	MSL 3 Rated item requir	es Bake and D	ry Pack (afte	r electrical test)												
or more infor	mation regarding materia	l composition	please refer t	o page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.79	mg	Supplier	Silicon (Si)	7440-21-3		1.79	mg
Die Attach	0.45	mg	Supplier	Silver (Ag)	7440-22-4		0.3375	mg
			Supplier	Epoxy resins	129915-35-1		0.1125	mg
Lead Frame	10.5	mg	Supplier	Silver (Ag)	7440-22-4		0.105	mg
			Supplier	Tin (Sn)	7440-31-5		0.0262	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0231	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0262	mg
			Supplier	Copper (Cu)	7440-50-8		10.3194	mg
Mold Compound-Black	12.08	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.9664	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0604	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.2416	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		10.4492	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.3624	mg
Plating	0.56	mg	Supplier	Tin (Sn)	7440-31-5		0.56	mg
Wire Bond - Au	0.1	mg	Supplier	Gold (Au)	7440-57-5		0.1	mg